Product / Package Information

Package	TSSOP
Body Size	4.4 mm
Lead Count	14
Terminal Finish	100Sn
MS Number	MS010627B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.84 E-02	87.70	877000	49.96	499582
Thermosets	Epoxy Resin	Proprietary	1.78 E-03	5.50	55000	3.13	31331
Thermosets	Phenol Resin	9003-35-4	1.78 E-03	5.50	55000	3.13	31331
Other inorganic materials	Antimony Trioxide	1309-64-4	1.94 E-04	0.60	6000	0.34	3418
Thermosets	Brominated Epoxy Resin	40039-93-8	1.30 E-04	0.40	4000	0.23	2279
Other inorganic materials	Carbon Black	1333-86-4	9.72 E-05	0.30	3000	0.17	1709
Subtotal			3.24 E-02	100.0	1000000	56.96	569648

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.79 E-02	97.57	975706	31.43	314278
Copper & its alloys	Iron	7439-89-6	4.17 E-04	2.28	22789	0.73	7340
Copper & its alloys	Zinc	7440-66-6	2.31 E-05	0.13	1263	0.04	407
Copper & its alloys	Phosphorus	7723-14-0	4.44 E-06	0.02	242	0.01	78
Subtotal			1.83 E-02	100.00	1000000	32.21	322104

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.85 E-04	100.0	1000000	0.33	3254

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.14 E-03	100.0	1000000	2.01	20103

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.11 E-04	99.99	1000000	0.55	5465

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.11 E-03	100.0	1000000	5.47	54651

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.13 E-03	80	800000	1.98	19820
Thermosets	Epoxy Resin	Proprietary	2.11 E-04	15	150000	0.37	3716
Others	Curing agent & hardener	Proprietary	7.04 E-05	5	50000	0.12	1239
Subtotal			1.41 E-03	100	1000000	2.48	24775

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.69 E-02**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

Product / Package Information

Package	TSSOP
Body Size	4.4 mm
Lead Count	14
Terminal Finish	SnPb
MS Number	MS010657B

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.84 E-02	87.70	877000	49.96	499582
Thermosets	Epoxy Resin	Proprietary	1.78 E-03	5.50	55000	3.13	31331
Thermosets	Phenol Resin	9003-35-4	1.78 E-03	5.50	55000	3.13	31331
Other inorganic materials	Antimony Trioxide	1309-64-4	1.94 E-04	0.60	6000	0.34	3418
Thermosets	Brominated Epoxy Resin	40039-93-8	1.30 E-04	0.40	4000	0.23	2279
Other inorganic materials	Carbon Black	1333-86-4	9.72 E-05	0.30	3000	0.17	1709
Subtotal			3.24 E-02	100.0	1000000	56.96	569648

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.79 E-02	97.57	975706	31.43	314278
Copper & its alloys	Iron	7439-89-6	4.17 E-04	2.28	22789	0.73	7340
Copper & its alloys	Zinc	7440-66-6	2.31 E-05	0.13	1263	0.04	407
Copper & its alloys	Phosphorus	7723-14-0	4.44 E-06	0.02	242	0.01	78
Subtotal			1.83 E-02	100.00	1000000	32.21	322104

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.85 E-04	100.0	1000000	0.33	3254

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	9.71 E-04	85.0	850000	1.71	17088
Tin & its alloys	Lead	7439-92-1	1.71 E-04	15.0	150000	0.30	3016
Subtotal			1.14 E-03	100.0	1000000	2.01	20103

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.11 E-04	99.99	1000000	0.55	5465

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.11 E-03	100.0	1000000	5.47	54651

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.13 E-03	80	800000	1.98	19820
Thermosets	Epoxy Resin	Proprietary	2.11 E-04	15	150000	0.37	3716
Others	Curing agent & hardener	Proprietary	7.04 E-05	5	50000	0.12	1239
Subtotal			1.41 E-03	100	1000000	2.48	24775

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.69 E-02**	100.00	1000000

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